

# Chip Scale Review

## 2017 Editorial Calendar

**(Editorial close date: 11/20)**

**January • February**

\* indicates show distribution

Industry forecast	<ul style="list-style-type: none"> <li>• <b>SEMI European 3D Summit</b> Grenoble, France (Jan 23-25)</li> <li>• <b>SMTA Pan Pac Microelectronics Symposium *</b> Kauai, Hawaii (Feb 6-9)</li> <li>• <b>SEMICON Korea</b> Seoul, Korea (Feb 8-10)</li> <li>• <b>APEX Expo</b> San Diego, CA (Feb 14-16)</li> <li>• <b>ISS Europe</b> Munich, Germany (March 5-8)</li> <li>• <b>BiTS Workshop*</b> <b>Mesa, AZ (March 5-8)</b></li> <li>• <b>IMAPS DPC*</b> Fountain Hills, AZ (March 6-9)</li> <li>• <b>SEMICON China*</b> Shanghai, China (March 14-16)*</li> </ul>
Future of packaging with silicon photonics	
FOWLP technology trends	
Cu pillars for 3D stacking	
Electroplating for packaging applications	
Electronic assembly reliability	
Metrology for lithography applications	
Package integration drives RF test complexity	
High frequency test sockets	

**Ad Space Close Jan 6 - Ad Materials Close Jan 11**

**(Editorial close date: 1/6)**

**March • April**

\* indicates show distribution

Metrology for advanced packaging applications	<ul style="list-style-type: none"> <li>• <b>SEMICON SE Asia</b> Penang, Malaysia (Apr 25-27)</li> <li>• <b>ECTC *</b> Lake Buena Vista, FL (May 30- June 2)</li> </ul>
Production readiness of 2.5D ICs	
3D integration technology for high-density, high performance ICs	
Glass-based SiP solutions	
Die attach solutions	
Electronic materials	
Embedded and fan-out packaging	
Testing of MEMS / sensors in HVM	
Wafer-level test	
Core capabilities of a thermocompression bonder	

**Ad Space Close Feb 17 - Materials Close Feb 24**

**(Editorial close date: 3/10)**

**May • June**

\* indicates show distribution

Thin wafer handling	<ul style="list-style-type: none"> <li>• <b>IEEE/SW Test Workshop (SWTW)</b> San Diego, CA (June 5-8)</li> <li>• <b>Meptec MEMS &amp; Sensors Symposium</b> San Jose, CA (June 6)</li> <li>• <b>IMAPS SiP 2017*</b> Sonoma, CA (June 27-29)</li> <li>• <b>Sensors Expo &amp; Conference</b> San Jose, CA (June 27-29)</li> <li>• <b>SEMICON West *</b> San Francisco, CA (July 12-14)</li> </ul>
3D technology failure analysis	
Advances in thermal management	
Adhesives, underfill, encapsulants	
WLCSPs	
Wafer probing	
Defect inspection	
Automotive application solutions	
Feature: 50 years of CEA-Leti – past, present, future	

**Ad Space Close April 21 - Ad Materials Close April 28**

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Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.

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